

Model:GH9492

OPERATION DESCRIPTION

■ **HANDSET**

1. RF/Audio Section

The radio link Handset and Base is full duplex at 2400/2483.5 MHz with the 40 channels. FM modulation is used for the link. The 1st IF frequency is 10.7MHz and the 2nd IF frequency is 450KHz. The operating frequency for the cordless phone is selected from one of the following channels and controlled by the synthesizer U2 that is programmed by the MCU.

This section is common to both handset and base as the same ICs are used LMX1602(U2), KA3361(U1) is made up of dual serial input PLL frequency synthesizer with 1000MHz prescaler. KA3361 is a narrow-band IF detector IC.

1.1 Receiver

The receiver section is made of double conversion with 10.7MHz as the first and second IF. Rx signal from the duplexer circuit is amplified by a Low Noise RF transistor and passed to 450KHz IF in the internet mixer of U1. Voice/data signal is demodulated and output from pin9 of U1. The demodulated signal is then divided into two paths, a path is fed into the data amplifier Q7, Q13. The other path will go through a de-emphasized amplifier and an expander in IC1. Recovered signal scan be muted by the pin 13 of IC 1, the volume level of the signal can be controlled by the push switch SW1.

1.2 Transmitter

Audio signal (from Microphone for headset/Tip & Ring for base) is first fed into the amplifier and compressor inside IC1 (U5 for Base). The signal will pass through a limiter. The AGC and the limiter have the property to limit the maximum signal that feed into the transmitter so that the RF deviation is limited. The transmitter section mainly divided into two parts. They are the voice/data modulator and the Tx power amplifier. The voltage-controlled oscillator VCO operated at the Tx frequency controlled by the synthesizer is modulated by the audio and data signals. Modulated signal is amplified by the RF amplified and sending the signal to the duplexer for radiation by the antenna.

1.3 Band-Pass Filter (BFF)

The function of the two Band-Pass Filter(BPF) is to individual fed the transmitting and receiving signals to a common antenna while providing isolation and rejection of interference and other spurious signals.

1.4 Alerter

The alerting signals include the following: Ringing, Paging, key beep and Low battery warning tone. These tones are generated by the MCU to the alerter through the driving circuit formed Q6 and the associated components.

1.5 Headset microphone

The condenser microphone is in the handset and it biased by the resistor R6 The signal is applied to the amplifier inside IC1.

2. MCU

2.1 Battery Detect

The voltage detector is composed of U1 that is used to detect battery low condition. The detecting accuracy of the voltage detector is +/- 0.2V. The detect pin BAT-LOW is connected to the pin 50 of MCU.

2.2 Carrier Detection

This 40 channels cordless has the features of auto-scanning. This is done by the detection of the RSSI at pin 70 of MCU of handset. During PHONE on or CHANNEL changing, the MCU will select the clearest channel for the RF communication.

■ BASE

3. RF/Audio sections

The operation of the RF/Audio section is similar to that of the handset.

4. Telephone Network

4.1 Telephone interface

Fuse FUSEx is for over-voltage protection. Transistor Q31, Q32 controls the on/off hook state and pulse dialing.

4.2 Ring Detect

When ring signal is present on the Tip Ring, and envelope waveform of the ring pattern will transfer to pin 3 of MCU by the LM324 pin 1 The MCU will read this waveform and determine whether it will send ringer command,

4.3 Sidetone Cancellation Network

The sidetone cancellation is a hybrid circuit of the Tx and Rx paths of the telephone circuit formed by the Q28.

5. MCU

5.1 Charging Network

Base charging circuit provides a DC current for handset battery. Resistor R31 controls the current flow.

5.2 Carrier Detection

This is similar to the handset counterpart.

6. Digital Answer System

Digital Answer System is consist of a DSP chip (MX93132,U7) and flash memory chip (MX29F400T, U4)

6.1 MX93132 provides speech processing/management modules, including speech compression/ decompression silence management, telephone line signal processing RAM Management line echo cancellation and acoustical echo cancellation, etc.

6.2 MX29F400T: Memory Chip – resources of DAS.